

LOC	DIST	REVISIONS					
GP	00	P	LTN	DESCRIPTION	DATE	DWN	APVD
		F3		REVISED PER ECO-18-008086	24MAY2018	IT	SH

1. MATERIAL:
 CAGE - 0.25mm THICK NICKEL SILVER ALLOY
 HEATSINK - ALUMINUM
 HEATSINK CLIP - STAINLESS STEEL
 EMI SPRING(S) - COPPER ALLOY

2. FINISH:
 HEATSINK - ELECTROLESS NICKEL
 HEATSINK CLIP - PASSIVATE
 EMI SPRING(S) - 0.8um MIN MATTE TIN OVER 0.8um MIN NICKEL,
 NON-PLATED EDGES PERMISSIBLE.

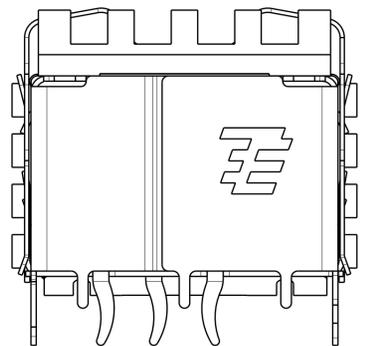
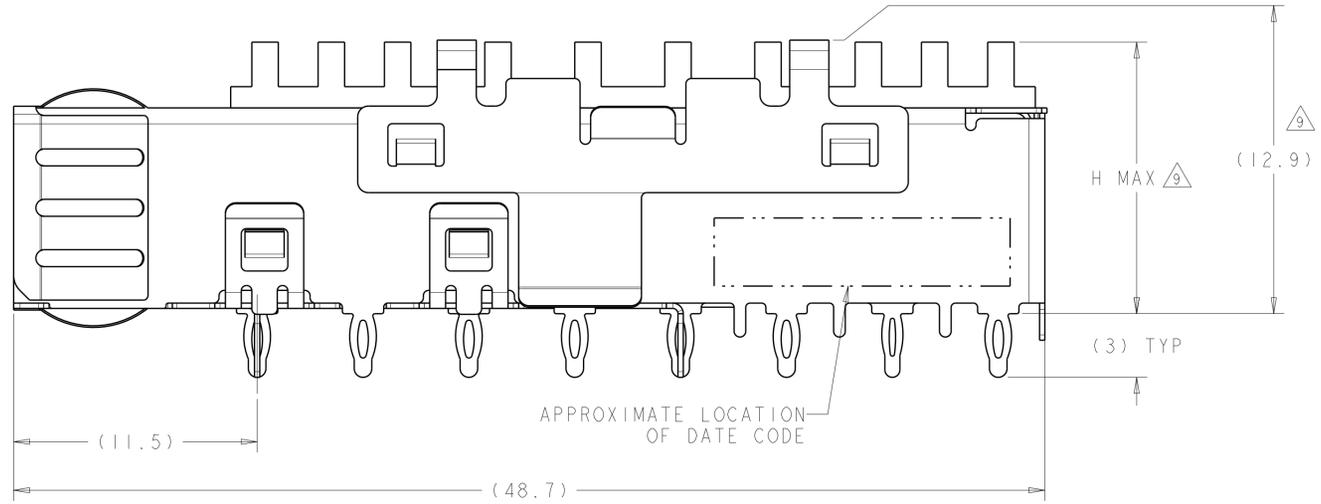
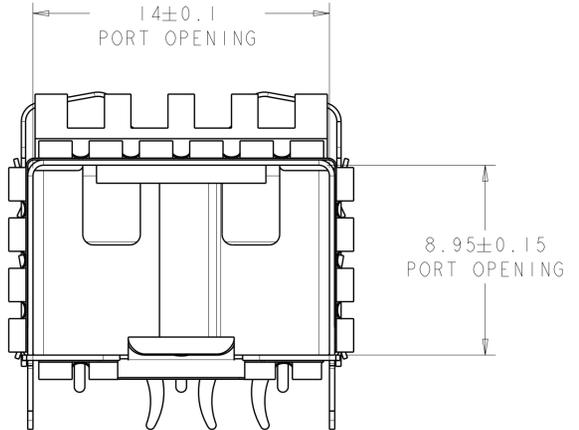
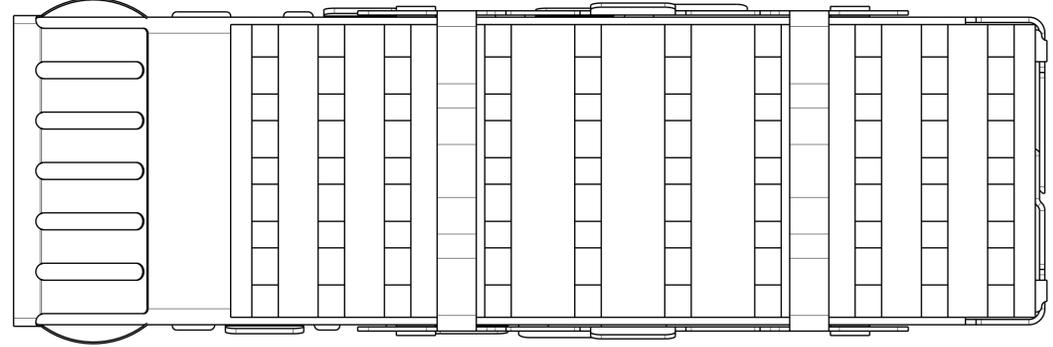
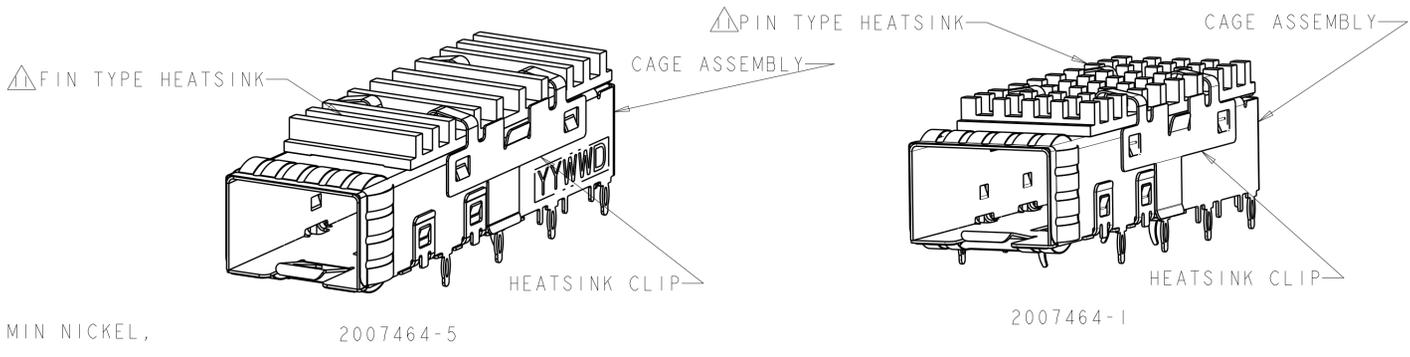
3. MATES WITH SFP MSA COMPLIANT TRANSCEIVERS.

4. PADS AND VIAS CHASSIS GROUND.

5. DATUM AND BASIC DIMENSION ESTABLISHED BY CUSTOMER.

6. MINIMUM PC BOARD THICKNESS:
 SINGLE SIDED = 1.50mm
 DOUBLE SIDED = 3.00mm

7. REFERENCE APPLICATION SPEC. 114-13120, HOLE A, FOR
 RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.



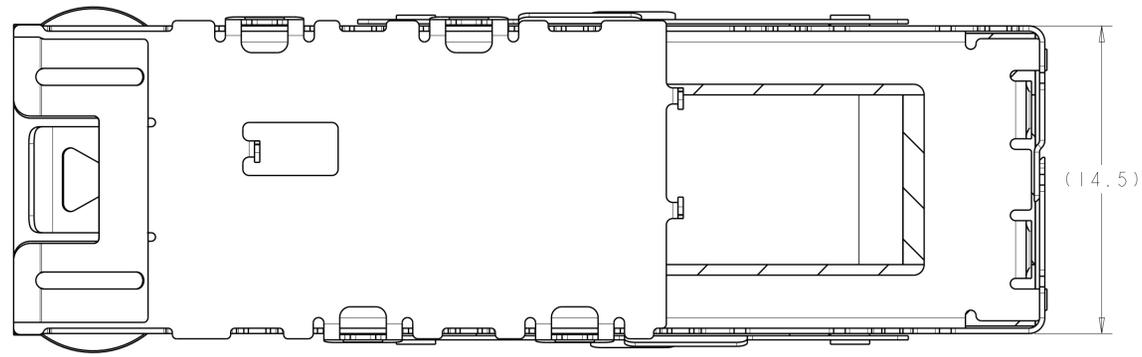
8. REFERENCE APPLICATION SPEC. 114-13120, HOLE C, FOR
 RECOMMENDED DRILL HOLE DIAMETER AND PLATING THICKNESS.

9. DIMENSION APPLIES PRIOR TO INSERTION OF SFP MODULE.

10. CAGE ASSEMBLY, HEATSINK CLIP AND HEATSINK SHIPPED
 ASSEMBLED.

11. HEAT SINK REFERENCE PART NUMBERS:
 1829903-2 = 4.2 HIGH - PCI, PIN TYPE
 1829904-2 = 6.5 HIGH - SAN, PIN TYPE
 1829905-2 = 13.5 HIGH - NETWORKING, PIN TYPE
 2170426-4 = 4.2 HIGH - PCI, PIN TYPE
 2170427-4 = 6.5 HIGH - SAN, PIN TYPE
 2170428-4 = 13.5 HIGH - NETWORKING, PIN TYPE

12. REMOVED



DESCRIPTION	H MAX	APPLICATION	PART NUMBER
W/O INSULATING TAPE	13.5	PCI	2007464-9
W/ INSULATING TAPE	22.8	NETWORKING	2007464-8
W/O INSULATING TAPE	22.8	NETWORKING	2007464-7
W/O INSULATING TAPE	15.8	SAN	2007464-6
W/O INSULATING TAPE	13.5	PCI	2007464-5
W/ INSULATING TAPE	22.8	NETWORKING	2007464-4
W/O INSULATING TAPE	22.8	NETWORKING	2007464-3
W/O INSULATING TAPE	15.8	SAN	2007464-2
W/O INSULATING TAPE	13.5	PCI	2007464-1

THIS DRAWING IS A CONTROLLED DOCUMENT. DWG: Z.M.BEAM 20NOV2007
 CHK: M.R.SCHMITZ 20NOV2007
 APVD: R.H.WERTZ 20NOV2007

TE Connectivity

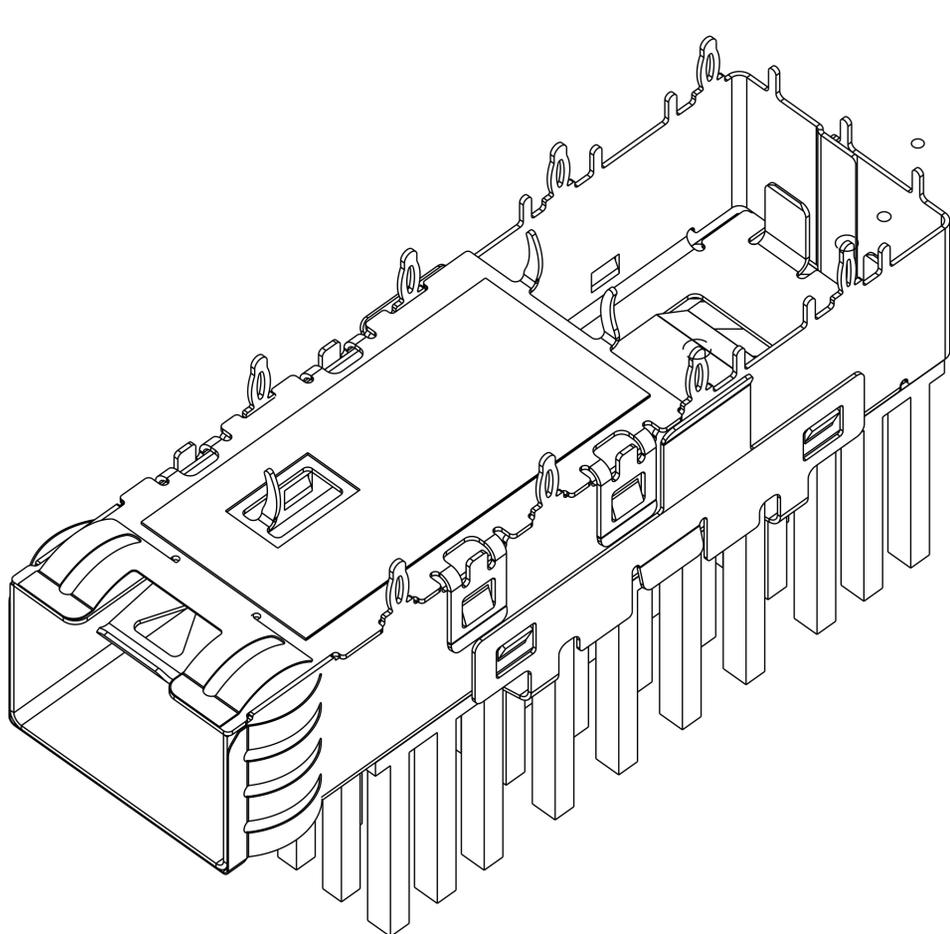
NAME: SFP+ IXI CAGE ASSEMBLY, PRESS-FIT PRESS-FIT, EMI SPRINGS WITH HEATSINK

PRODUCT SPEC: 108-2364
 APPLICATION SPEC: 114-13120

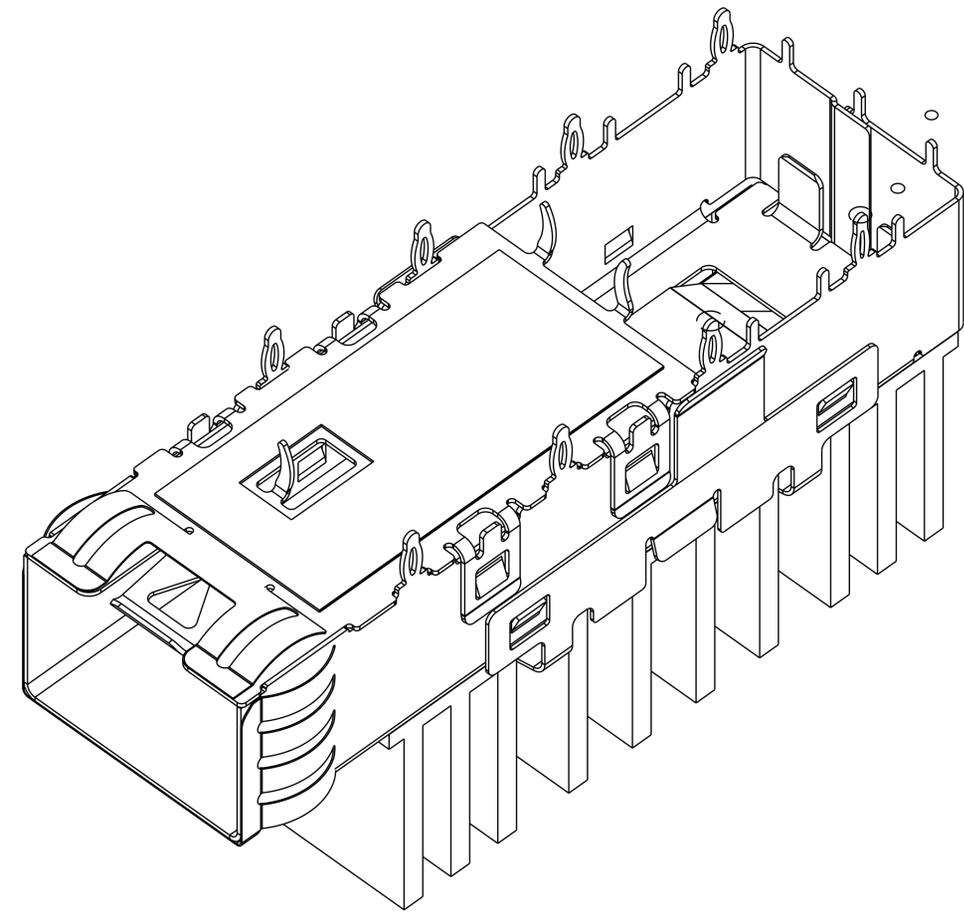
SIZE: A1
 CAGE CODE: 00779
 DRAWING NO: 2007464

Customer Drawing SCALE: 6:1 SHEET 1 OF 4 REV: F3

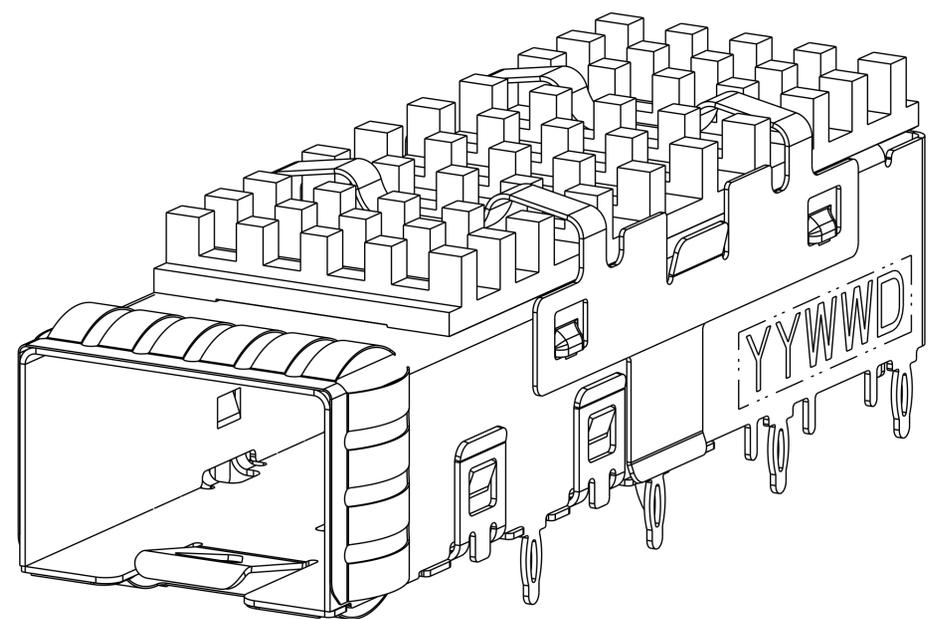
LOC	DIST	REVISIONS			
P	LYR	DESCRIPTION	DATE	DMN	APVD
GP	00	SEE SHEET 1			



2007464-4 AS SHOWN WITH INSULATING TAPE, PIN TYPE HEAT SINK
 2007464-1,2,3 WITHOUT INSULATING TAPE, TAPE, PIN TYPE HEAT SINK



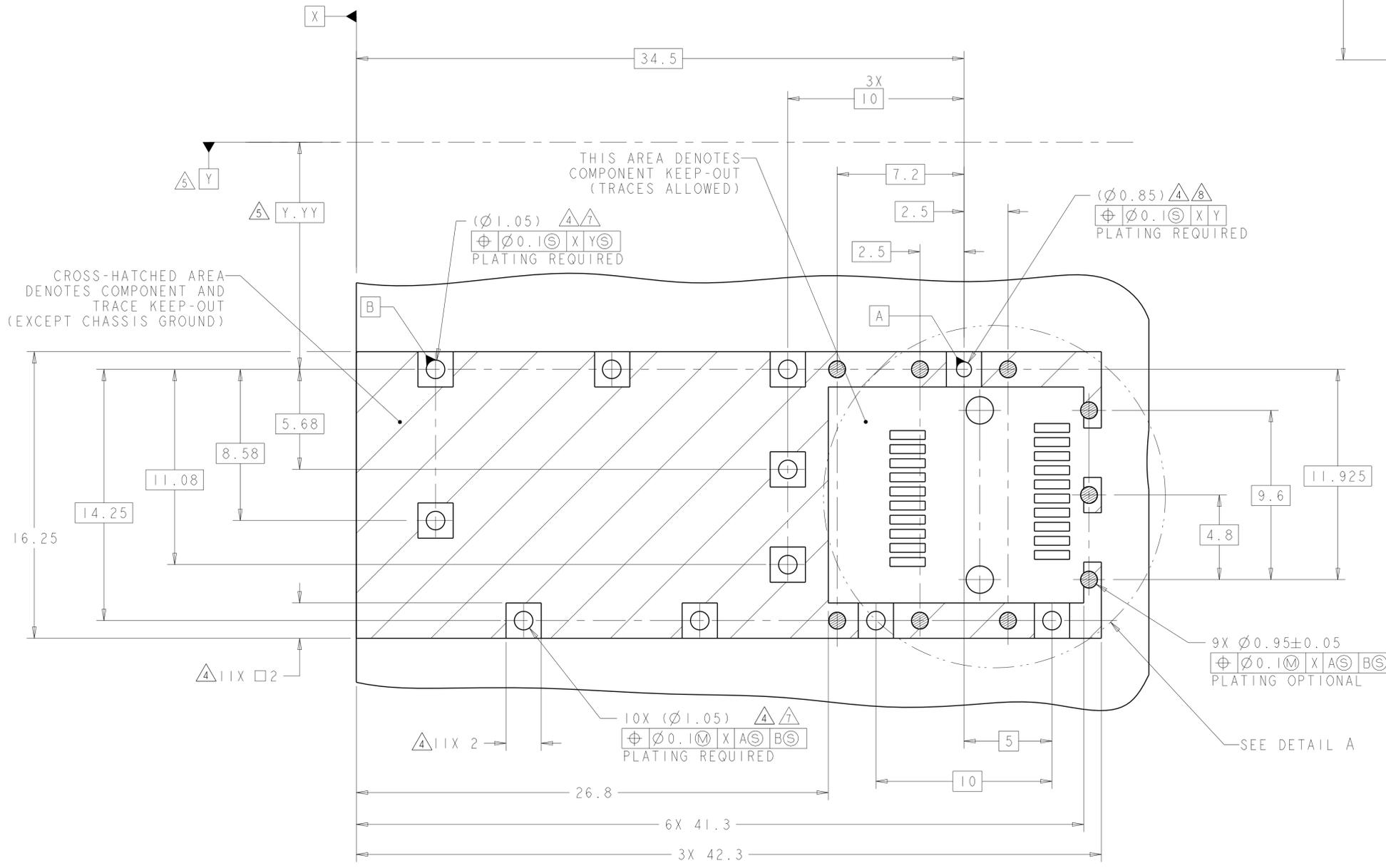
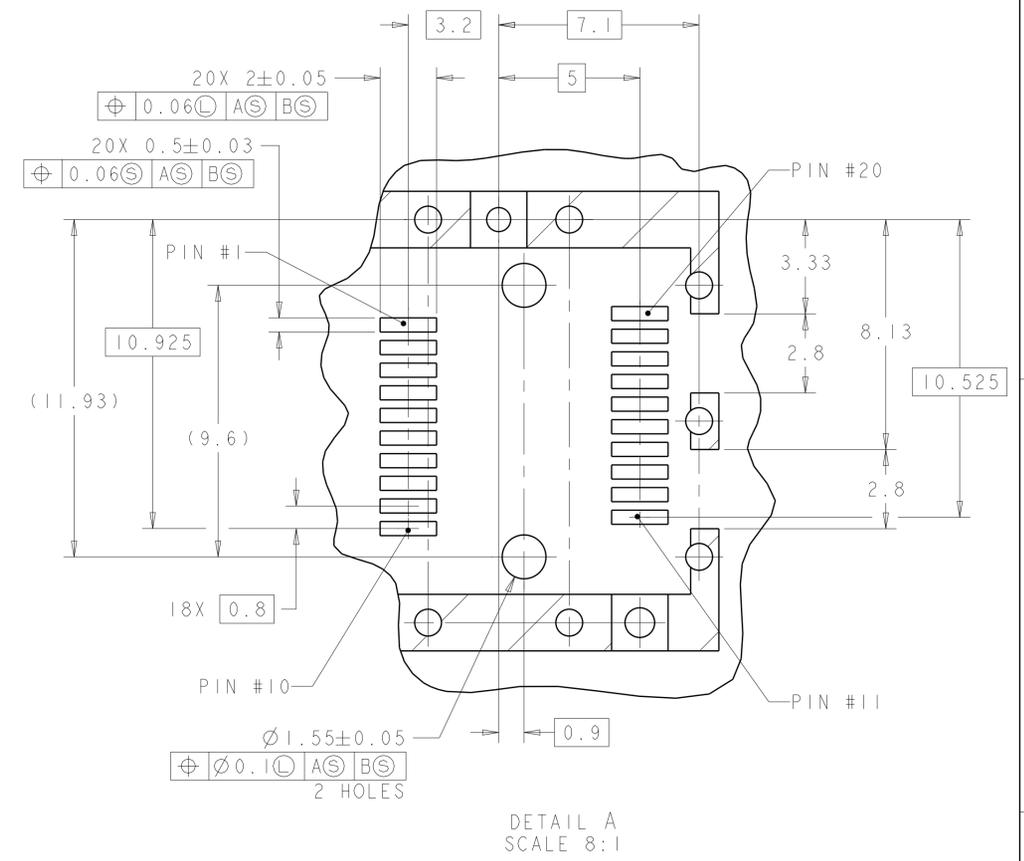
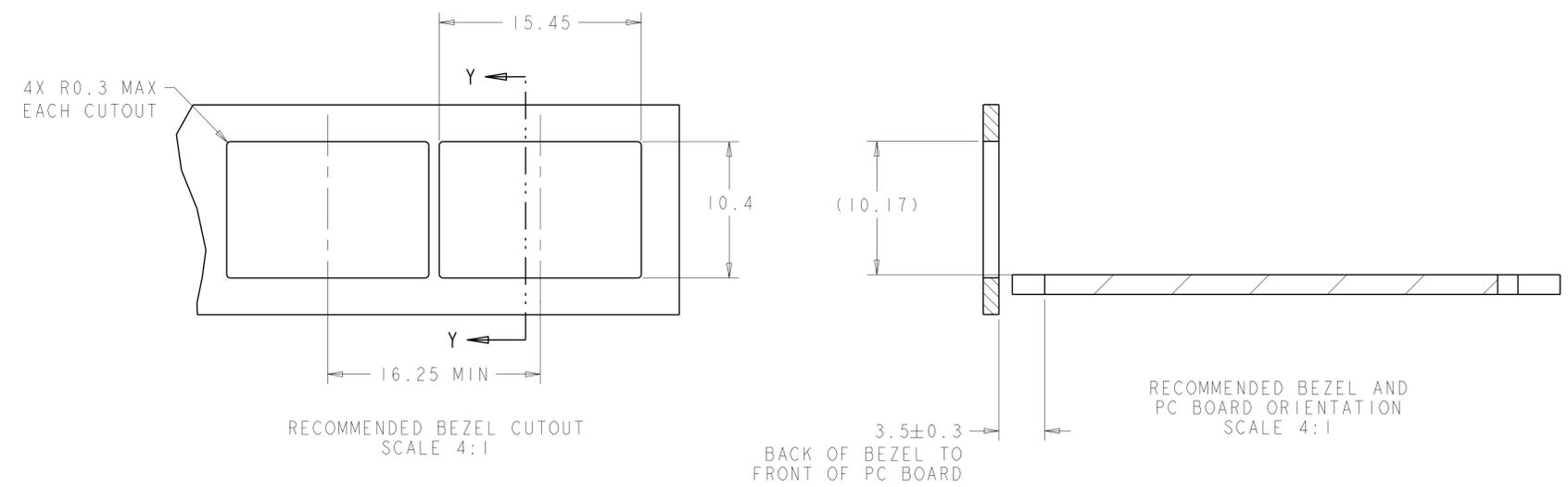
2007464-8 AS SHOWN WITH INSULATING TAPE, WITH FIN TYPE HEAT SINK
 2007464-5,6,7 WITHOUT INSULATING TAPE, WITH FIN TYPE HEAT SINK



2007464-9 AS SHOWN

THIS DRAWING IS A CONTROLLED DOCUMENT.		DMN Z.M.REAM 20NOV2007	TE Connectivity
DIMENSIONS:		CHK M.R.SCHMITZ 20NOV2007	
mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	APVD R.H.WERTZ 20NOV2007	NAME SFP+ IXI CAGE ASSEMBLY, PRESS-FIT PRESS-FIT, EMI SPRINGS WITH HEATSINK
0 PLC ±0.1	1 PLC ±0.1	PRODUCT SPEC 108-2364	SIZE CAGE CODE DRAWING NO RESTRICTED TO
2 PLC ±0.1	3 PLC ±0.05	APPLICATION SPEC 114-13120	A100779C=2007464
4 PLC ±0.05	ANGLES ±0.05	WEIGHT	SCALE 2 SHEET 2 OF 4 REV F3
MATERIAL FINISH		Customer Drawing	

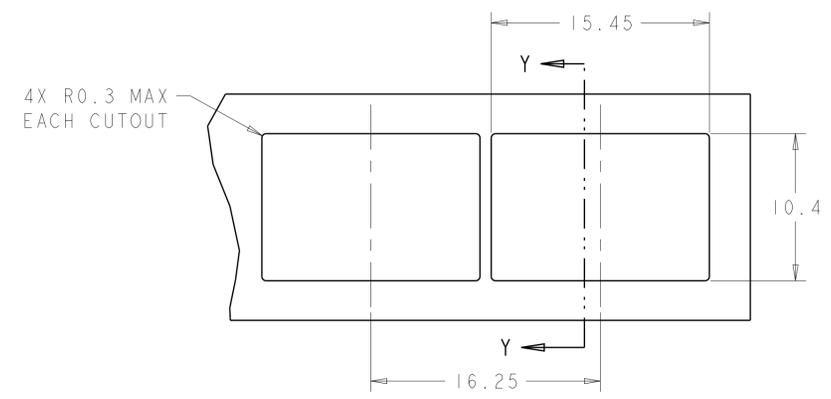
LOC	DIST	REV	DESCRIPTION	DATE	OWN	APVD
GP	00		SEE SHEET 1			



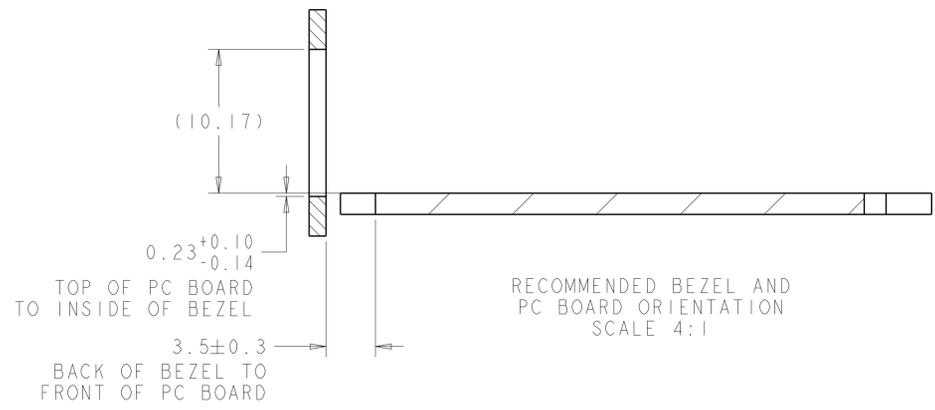
RECOMMENDED PCB LAYOUT
SCALE 7:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN: Z.M. BEAM 20NOV2007	TE Connectivity
DIMENSIONS: mm		CHK: M.B. SCHMITZ 20NOV2007	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD: B.H. WERTZ 20NOV2007	NAME: SFP+ IXI CAGE ASSEMBLY, PRESS-FIT PRESS-FIT, EMI SPRINGS WITH HEATSINK
0 PLC ±0.1	1 PLC ±0.1	PRODUCT SPEC: 108-2364	SIZE: CAGE CODE DRAWING NO: A100779C=2007464
2 PLC ±0.1	3 PLC ±0.05	APPLICATION SPEC: 114-13120	RESTRICTED TO: -
4 PLC ±0.05	ANGLES ±0.05	WEIGHT: -	SCALE: 2 SHEET 3 OF 4 REV: F3
MATERIAL: -	FINISH: -	Customer Drawing	

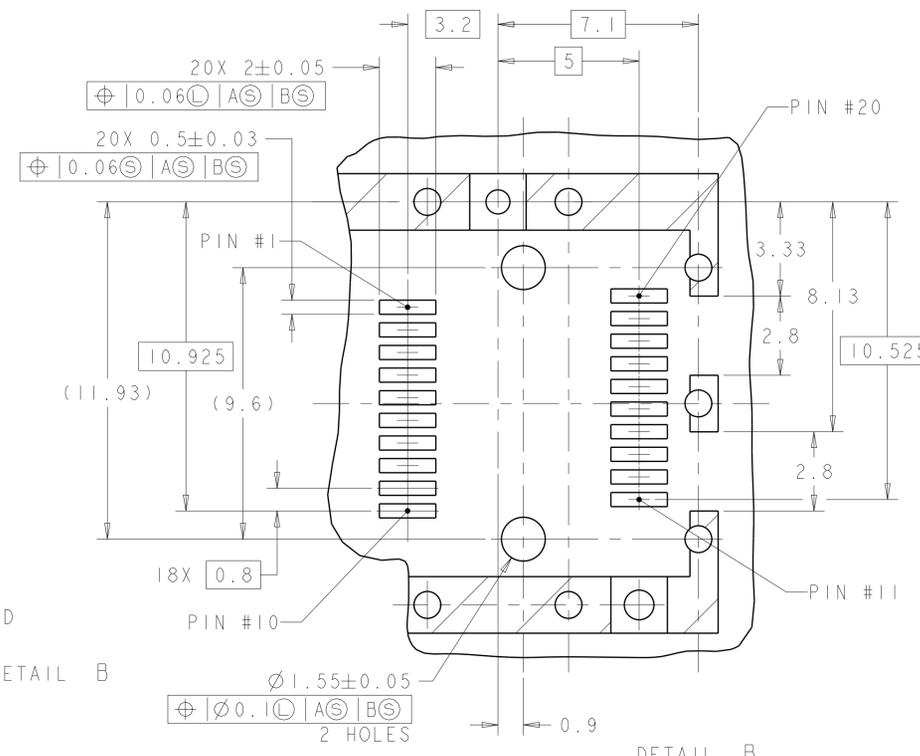
LOC	DIST	REV	DATE	APPD	APVD
GP	00				
		REVISIONS			
		DESCRIPTION	DATE	OWN	APVD
		SEE SHEET 1			



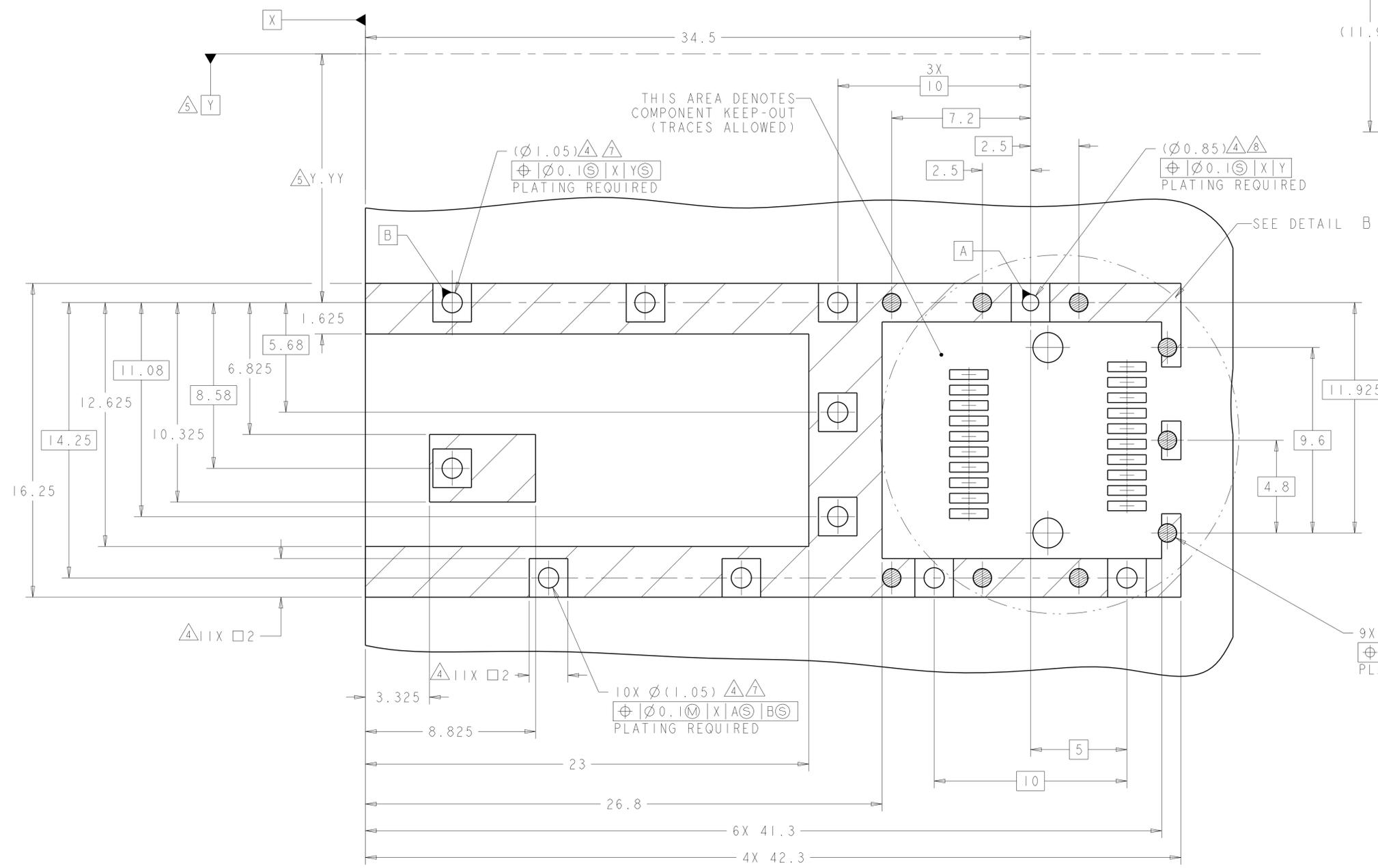
RECOMMENDED BEZEL CUTOUT
SCALE 4:1



RECOMMENDED BEZEL AND
PC BOARD ORIENTATION
SCALE 4:1



DETAIL B
SCALE 8:1



RECOMMENDED PCB LAYOUT FOR WITH
INSULATING TAPE PART
SCALE 8:1

THIS DRAWING IS A CONTROLLED DOCUMENT.		OWN: Z.M.BEAM 20NOV2007	TE Connectivity
DIMENSIONS: mm		CHK: M.R.SCHMITZ 20NOV2007	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APPD: B.H.WERTZ 20NOV2007	NAME: SFP+ IXI CAGE ASSEMBLY, PRESS-FIT PRESS-FIT, EMI SPRINGS WITH HEATSINK
0 PLC ±0.1		PRODUCT SPEC: 108-2364	SIZE: A100779C=2007464
1 PLC ±0.1		APPLICATION SPEC: 114-13120	RESTRICTED TO: -
2 PLC ±0.1		WEIGHT: -	SCALE: 2 SHEET 4 OF 4 REV: F3
3 PLC ±0.05		MATERIAL: -	
4 PLC ±0.05		FINISH: -	
ANGLES ±0.05		Customer Drawing	

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9